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1994TW-0111239

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G03F007/20 ,  
H01L021/027

ABSTRACTED-PUB-NO: JP 07168345A

BASIC-ABSTRACT:

In a pericle for lithography, a pericle film of a polymer is bonded on a pericle frame by using an adhesive agent of polymer, glass transition temp. of the adhesive agent is lower than that of the pericle film.

USE/ADVANTAGE - In anti refuse material in mfr. of semiconductor device such as LSI or mfr. of liquid crystal display. If the pericle film is heated at higher temp. than the glass transition temp. of the adhesive agent so as to improve this adhesive intensity, the temp. of the pericle film will not rise higher than the glass transition temp. Thereby, generation of crinkling and depression on the pericle film can be prevented.

In an example, the pericle film was formed by coating a prepd. soln. on a quartz substrate and forming a transparent film and drying the film.

ABSTRACTED-PUB-NO: US 5693382A

EQUIVALENT-ABSTRACTS:

In a pericle for lithography, a pericle film of a polymer is bonded on a pericle frame by using an adhesive agent of polymer, glass transition temp. of the adhesive agent is lower than that of the pericle film.

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In an example, the pericle film was formed by coating a  
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quartz substrate and forming a transparent film and drying  
the film.

CHOSEN-DRAWING: Dwg.0/0 Dwg.0/0

TITLE-TERMS: LITHO POLYMERISE FILM BOND FRAME ADHESIVE  
LOWER GLASS TRANSITION  
TEMPERATURE FILM

DERWENT-CLASS: G06 L03 P84

CPI-CODES: G06-A08; G06-D06; L04-C06B;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1995-121176

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DERWENT-ACC-NO: 1995-266297

DERWENT-WEEK: 200335

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TITLE: Pericle for lithography - has  
polymeric pericle film bonded to frame using adhesive having  
lower glass transition temp. than that of film

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PATENT-FAMILY:

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JP 07168345 A		July 4, 1995	N/A
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US 5693382 A		December 2, 1997	N/A
006	A47G	001/12	
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APPLICATION-DATA:

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